



Material Content Data Sheet



Sales Product Name		TLS850B0TE V33		Issued		1. August 2018		
MA#		MA001655148						
Package		PG-TO252-5-11		Weight*		363.07 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.422	0.39	0.39	3916	3916
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		169	
	non noble metal	iron	7439-89-6	0.205	0.06		563	
	non noble metal	copper	7440-50-8	204.243	56.25	56.33	562548	563280
	non noble metal	aluminium	7429-90-5	0.188	0.05	0.05	517	517
wire	non noble metal	aluminium	7429-90-5	0.188	0.05	0.05	517	517
encapsulation	organic material	carbon black	1333-86-4	0.301	0.08		828	
	plastics	epoxy resin	-	13.827	3.81		38083	
	inorganic material	silicondioxide	60676-86-0	136.163	37.50	41.39	375037	413948
leadfinish	non noble metal	tin	7440-31-5	5.072	1.40	1.40	13971	13971
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	210	211
solder	non noble metal	tin	7440-31-5	0.030	0.01		83	
	noble metal	silver	7440-22-4	0.038	0.01		104	
	non noble metal	lead	7439-92-1	1.441	0.40	0.42	3970	4157
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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